AMENDMENTS TO THE SPECIFICATION

I. Please replace the original TITLE with the following amended TITLE:

~~SELF-ADHESIVE FRAME APPLIED IN PACKAGE OF~~ FIELD EMISSION DISPLAY ~~, THE MANUFACTURING METHOD FOR THE SAME AND THE PACKAGE METHOD BY THE SAME~~ HAVING SELF-ADHESIVE FRAME

II. Please replace the two consecutive paragraphs beginning on page 4, line 7, and ending on page 5, line 2, with the following amended paragraphs:

In the process of package, first step is to spread the glass glue 108 on the alignment marked location of top base glass plate 100 for the glass side strip 106, then the operator places the glass side strip 106 on the alignment marked location. Through the first pre-heating to fix the glass side strip 106 on the top base glass plate 100, the operator should spread the glass glue 108 on another surface of the fixed glass side strip 106 to proceed to one more pre-heating process to oxidize the organic solvent in the glass glue 108. The following step is to proceed to the temporary fixing by a kind of certain UV glue for the bonding of the bottom base glass plate 110 and the top base glass plate 100 through alignment. The purpose of

the said temporary fixing is to keep the precision to prevent the distortion. The general application for temporary fixing is applied by the UV glue.

After the temporary fixing, the operator ~~apply~~ applies a kind of the fixing tool to fix the cathode plate 122 and the anode plate 120, proceeding to high temperature heat treatment as fritting. Thus the connection of the glass side strip 106 between the bottom base glass plate 110 and the top base glass plate 100 will be formed. But the UV glue will be decomposed in the high temperature treatment to pollute the glass glue. So the location of UV glue for the temporary fixing will be arranged as far as possible from the location of glass glue.

III. Please replace the paragraph on page 7, lines 18 - 20, with the following amended paragraph:

For the above mentioned, the inventor design a self-adhesive frame applied in package of field emission display to resolve the above mentioned problems. Please refer to the below description.

IV. Please replace the paragraph on page 8, lines 17 - 23, with the following amended paragraph:

The ~~Since~~ the prior ~~is~~ art easily ~~to~~ generates the problem of nonuniform ~~high~~ spreading of the high temperature glue ~~spreading~~. This condition will cause ~~the~~ a displacement action between the cathode plate 122 and the anode plate 120. Thus, the glass glue will generate ~~the~~ a slipping condition ~~in the~~ during the high temperature heat treatment ~~of high temperature by the nonuniform pressing fixing~~. ~~In the contrary~~ Whereas, the present invention has ~~the~~ a high uniformity at the package surface that can overcome the problem of nonuniform high spreading of the high temperature glue ~~spreading~~.

V. Please replace the paragraph on page 9, lines 8 - 14, with the following amended paragraph:

The main purpose of the present invention is to provide a structure suitable to the current manufacture process and low operation cost to provide an effect of low cost with high quality. The present invention ~~is to~~ provides a self-adhesive frame to overcome the problem of an increasing ~~of~~ void area and provides an effective usage of temporary fixing of the frame. In addition, provides a ~~package~~

packaging process for the cathode plate 122 and the anode plate 120 to reduce the alignment error and the distortion ~~occurred~~ that occurs in the fritting process.

VI. Please replace the paragraph beginning on page 13, line 2, and ending on page 14, line 1, with the following amended paragraph:

Base on the features of the self-adhesive frame 404, hereby provide a practical embodiment of package method by using the self-adhesive frame 404 on the field of field emission display. Firstly make alignment mark on the cathode plate 122 and the anode plate 120 and the mark is relative to the self-adhesive frame 404, the marked condition being general shown as the Fig. 5 and Fig. 6 described. Then spreading the UV glue on the sealing surfaces of fixing side strip 402, the sealing surface including the surface relative to the cathode plate 122 and the anode plate 120. Through a process of alignment action, the operator can easily install the self-adhesive frame 404 on the alignment mark of the cathode plate 122 and the anode plate 120 to cooperate with the UV source to solidify the UV glue to finish the temporary fixing process. Since the self-adhesive frame 404 is coated on certain surface by a glass glue 403 through heat treatment, the structure of temporary fixing process with the cathode plate 122 and the anode plate 120 can cooperate with a clipping device to be put into the heating stove. The

stove can provide heating temperature of 460 centigrade to melt the glass glue 403. From the special pre-treatment of planarization on the self-adhesive frame 404, the coating layer of glass glue 403 can obviously reduce the distortion during fritting. Please refer to the Fig. 7 for the sectional structure of the present invention. Wherein the sealing face in Fig. 7 is ~~rather~~ smaller than the sealing face in the second prior art. The present invention can greatly reduce the void region and raise the utilization of picture area. In addition, the location of temporary fixing can be arranged at the side of the cathode conductor 501 or the side of the anode conductor 601 to simply the consideration of location of the temporary fixing.